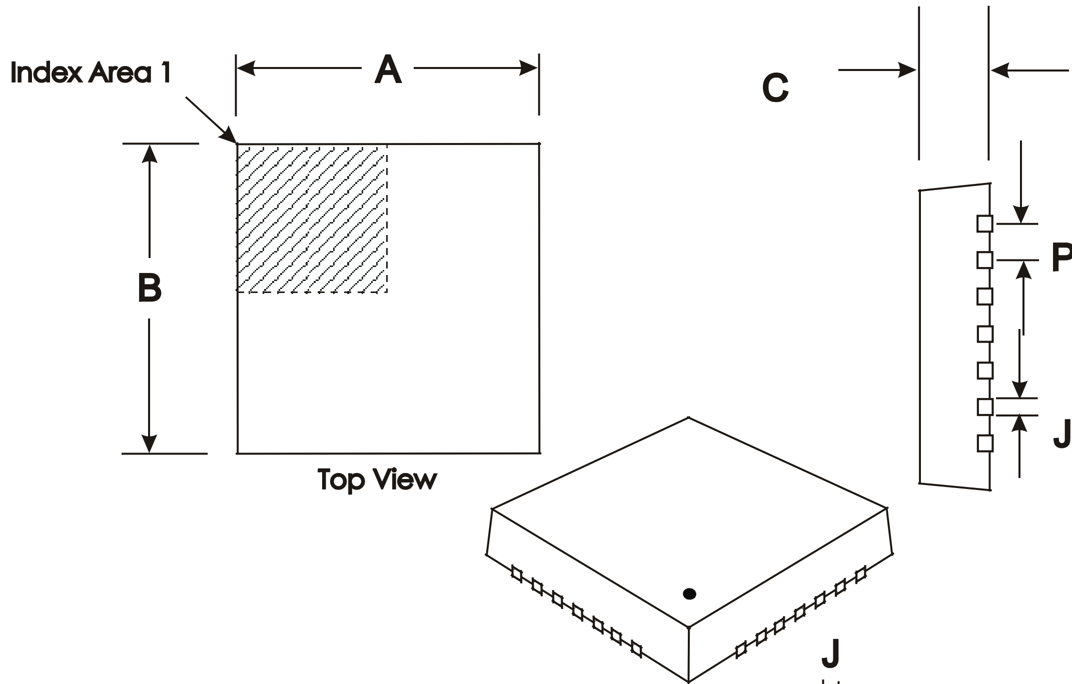
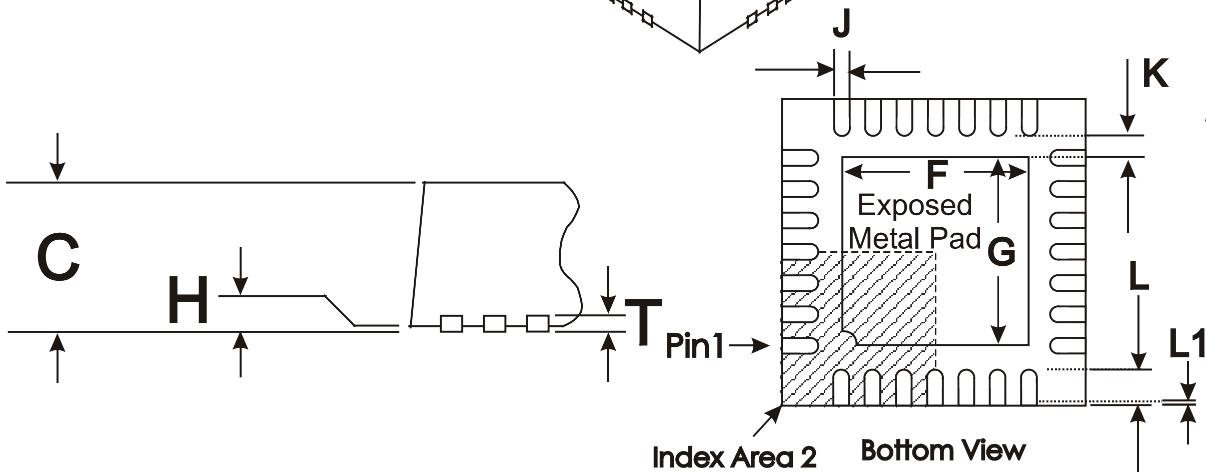


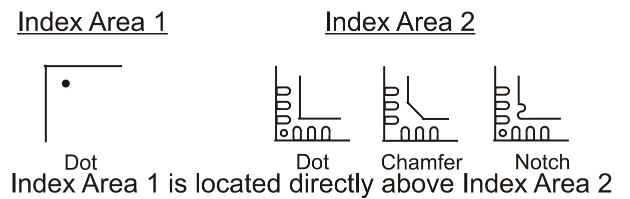
DIM.	MIN.	TYP.	MAX.
* A		5.00 BSC	
* B		5.00 BSC	
C	0.65	0.75	0.85
F	2.90		3.75
G	2.90		3.75
H	0.00		0.05
J	0.18	0.25	0.30
K	0.20		
L	0.35		0.75
L1	0		0.15
P		0.50	
T		0.20	



NOTE :

* A & B are reference data and do not include mold deflash or protrusions.

All dimensions in mm
Angles are in degrees



Index Area 1 is located directly above Index Area 2

Depending on the method of lead termination at the edge of the package, pull back (L1) may be present.
L minus L1 to be equal to, or greater than 0.3mm
The underside of the package has an exposed metal pad which should ideally be soldered to the pcb to enhance the thermal conductivity and mechanical strength of the package fixing. Where advised, an electrical connection to this metal pad may also be required

CML Microcircuits
COMMUNICATION SEMICONDUCTORS

Title	Drawing No. QT8	
28 pin WQFN package	D'WN by S.D.F	© CML 2016
		Issue: 1